

MATERIAL DECLARATION SHEET



Material Number	SF-1210SxxxW			
Product Line	Lead Free Slow Blow Wire Core Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Body	Epoxy Board	16.2568	Carbon	7440-44-0	41.25%	24.60%	62.96%
				Oxygen	7782-44-7	36.15%	21.56%	
				Silicon	7440-21-3	18.23%	10.87%	
				Hydrogen	1333-74-0	3.75%	5.55%	
				Aluminum	7429-90-5	0.26%	0.16%	
				Calcium	7440-70-2	0.36%	0.21%	
2	Fuse Link	Copper Composite Wire	0.1052	Alloy	Trade secret	68.03%	0.29%	0.41%
				Copper	7440-50-8	31.97%	0.12%	
3	Copper Layer (Termination)	Copper	7.6896	Copper	7440-50-8	100.00%	29.77%	29.77%
4	Nickel Layer (Termination)	Nickel	1.1255	Nickel	7440-02-0	100.00%	5.31%	4.36%

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5	Tin Layer (Termination)	Tin	0.5628	Tin	7440-31-5	100.00%	2.66%	2.18%
6	Marking	Marking Ink	0.0525	Carbon	7440-44-0	34.81%	0.11%	0.32%
				Oxygen	7782-44-7	28.34%	0.09%	
				Barium	7440-39-3	23.29%	0.08%	
				Hydrogen	1333-74-0	3.03%	0.01%	
				Silicon	7440-21-3	4.03%	0.01%	
				Magnesium	7439-95-4	1.02%	0.00%	
				Sulfur	7704-34-9	5.44%	0.02%	
				Nitrogen	7727-37-9	0.07%	0.00%	
		Total weight	25.7924					

This Document was updated on: 8-30-2017

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.